# ememory

### **1Q 2018 Investor Conference**

May 10<sup>th</sup>, 2018

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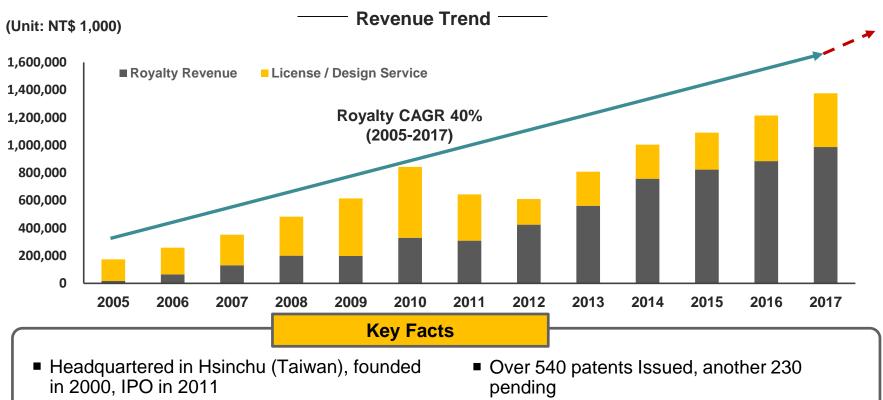


## Outline

- Company Overview
- Review of Operations for 1Q 2018
- Security IP NeoPUF introduction
- Future Outlook
- Q & A

## **Company Overview**

eMemory is the global leader of embedded non-volatile memory IP



- 100% gross margins, 48.4% OP margins
- Ranking no. 7 semiconductor IP vendor
- Over 20 mlns of wafers shipped.

- 244 employees (70% R&D personnel)
- Largest embedded NVM IP vendor
- TSMC Best IP Partner Award since 2010

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#### **Embedded Wisely, Embedded Widely**

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### **Worldwide Customers**

Our IP solutions are adopted by leading foundries, IDMs and fabless worldwide

#### Global Customers

	Foundry	IDM	Fabless
Taiwan	5	0	259
China	8	0	512
North America	1	2	240
Europe	2	1	109
Korea	3	0	75
Japan	3	8	52
Others	1	0	53





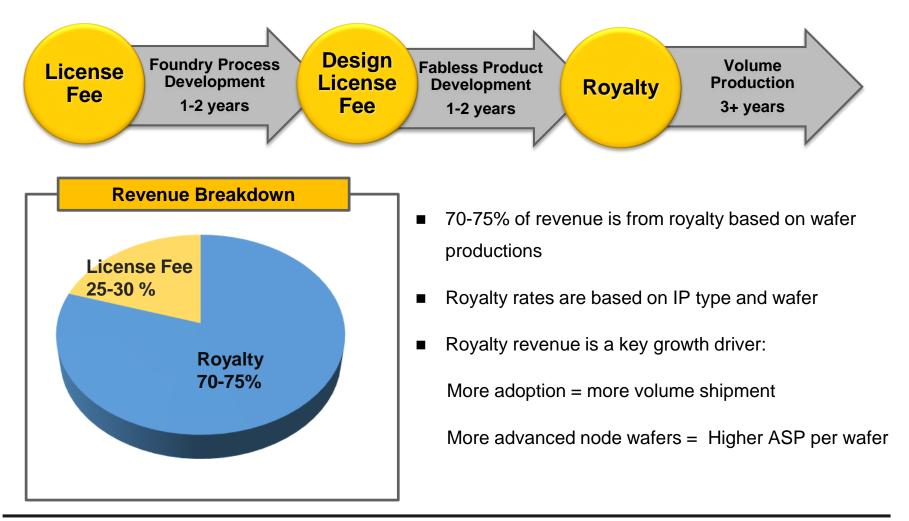
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### **Business Model**

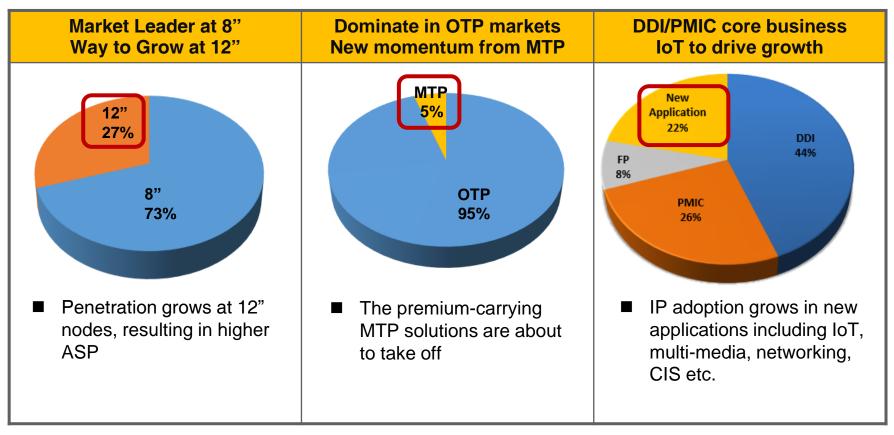
Recurring royalty is the backbone of our business



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## **Growth Engines**

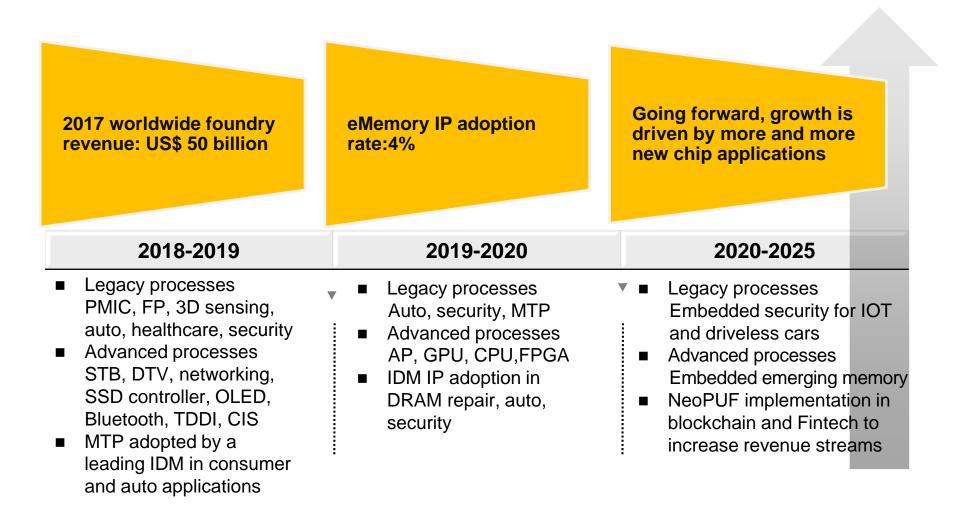
What supports our current growth, What drives our Future Growth



As of 2017

### **Growth Prospects**

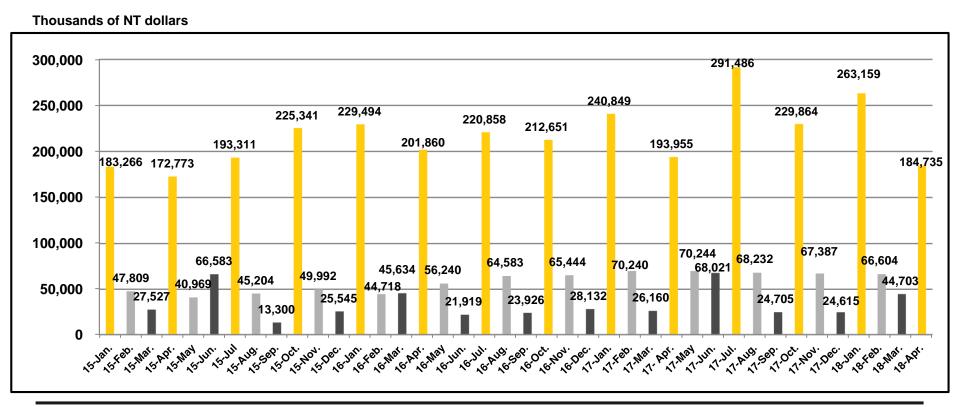
Our near-term, medium-term and long-term growth engines





### **Quarterly Revenue Pattern**

- 1st month: Receive License Fees of the month and Royalty from most foundries on previous quarter's wafer shipments
- 2<sup>nd</sup> month: Receive License Fees of the month and Royalty from other foundries
- 3<sup>rd</sup> month: License Fees Only.



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### **Q1 Revenue Breakdown**

#### Revenue (thousands of NT dollars)

	Q1 2018	Q4 2017	QoQ	Q1 2017	YoY	2017	2016	ΥοΥ
Licensing	114,540	78,811	45.3%	74,146	54.5%	388,184	330,087	17.6%
Royalty	259,926	243,055	6.9%	263,103	-1.2%	987,574	885,372	11.5%
Total	374,466	321,866	16.3%	337,249	11.0%	1,375,758	1,215,459	13.2%

#### Revenue (thousands of US dollars)

	Q1 2018	Q4 2017	QoQ	Q1 2017	ΥοΥ	2017	2016	ΥοΥ
Licensing	3,898	2,620	48.8%	2,384	63.5%	12,787	10,256	24.7%
Royalty	8,828	8,066	9.4%	8,366	5.5%	32,311	27,422	17.8%
Total	12,726	10,686	19.1%	10,750	18.4%	45,098	37,678	19.7%

#### Number of Licenses

		Q1 2018	Q4 2017	2017	2016
Technology Licenses		7	3	20	43
Design	NRE	15	15	55	56
Licenses	Usage	87	78	325	311

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## **Financial Income Statement**

Amount in Thousands of NT Dollars, except margins/EPS/ROE

	Q1 2018	Q4 2017	Q1 2017	change (QoQ)	change (YoY)
Revenue	374,466	321,866	337,249	16.3%	11.0%
Gross Margin	100%	100%	100%	-	-
Operating Expenses	193,201	185,484	193,603	4.2%	-0.2%
Operating Margin	48.4%	42.4%	42.6%	6.0ppts	5.8ppts
Net Income	168,730	117,659	151,378	43.4%	11.5%
Net Margin	45.1%	36.6%	44.9%	8.5ppts	0.2ppts
EPS	2.23	1.55	2.00	43.9%	11.5%
ROE	31.3%	23.6%	30.2%	7.7ppts	1.1ppts

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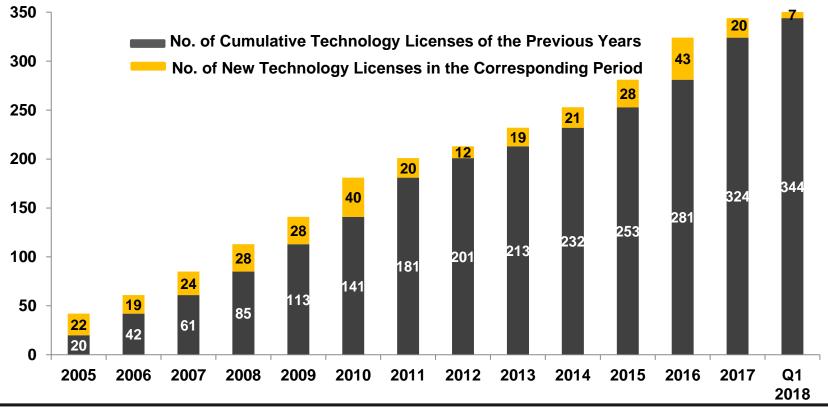


## **Technology Licensing**

#### **Number of Licenses**

Year	2015	2016	2017	Q1 2018
License	28	43	20	7

Note: Terms (including number of process platforms and licensing fees) for each technology license are set contractually. Payments are made according to set milestones, and there are no particular seasonal factors involved.



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### **New Technologies Under Development**

- New technologies being developed for 100 platforms by Q1 18.
- 15 for NeoBit, 45 for NeoFuse, 4 for NeoPUF, 11 for NeoEE, and 25 for NeoMTP.

	7/10nm	12/14/16nm	22/28nm	40nm	55/65nm	80/90nm	0.11~ 0.13um	0.15~ 0.18um
NeoBit	-	-	-	-	1	1	7	6
NeoFuse	3	3	12	6	6	9	3	3
NeoPUF	-	-	2	-	2	-	-	-
NeoEE	-	-	-	-	-	-	1	10
NeoMTP	-	-	-	1	2	2	7	13

As of March 31st, 2018



### **Technology Developments by Processes**

12" Fabs	Production	Development	ІР Туре	Process Type
7/10nm	0	3	ОТР	FF
12/14/16nm	2	3	ОТР	FF+
22/28nm	11	14	NeoPUF, OTP	LP/HPM, HLP/HPM, LPS, DRAM
40nm	10	7	OTP, MTP	HV-DDI, LP, eFlash
55/65nm	17	11	NeoPUF, OTP, MTP	LP, HV-DDI, HV-OLED, CIS, eFlash
80/90nm	7	9	OTP, MTP	HV-DDI, HV-OLED, LP, eFlash
0.13/0.11um	10	5	OTP, MTP	HV-DDI, BCD, Generic
0.18um	1	0	ОТР	BCD
Total	58	52		
8" Fab	s D	evelopment	IP Type	Process Type
90nm			OTP	HV-DDI, LL

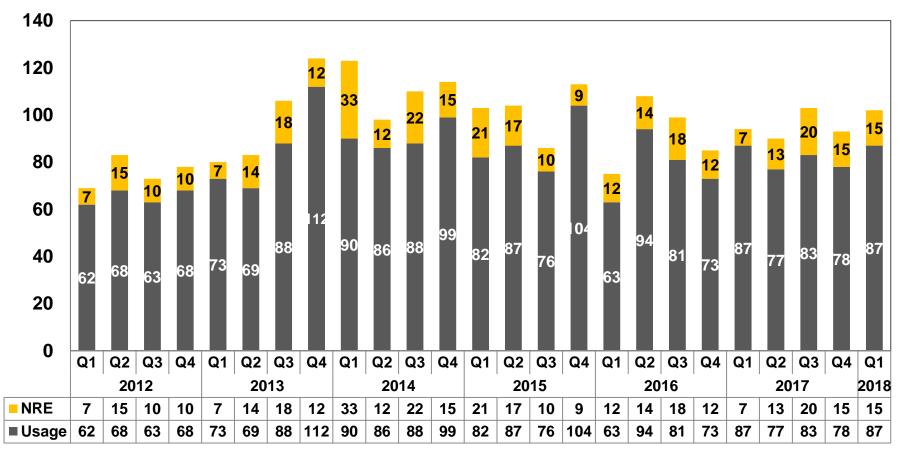
Development	іг туре	FIOLESS Type
3	OTP	HV-DDI, LL
13	OTP, MTP	HV-DDI, BCD, LP, RF, CIS, LL, Green
32	OTP, MTP	Generic, LP, LL, MR, HV, Green, BCD
0	OTP, MTP	BCD
0	OTP	UHV
48		
	3 13 32 0 0	3 OTP   13 OTP, MTP   32 OTP, MTP   0 OTP, MTP   0 OTP, MTP

Note: As of March 31st, 2018



## Design Licensing (New Tape-Out)

- A total 102 NTO in Q1 2018 (380 NTO in 2017, 367@2016, 406@2015, 445@2014)



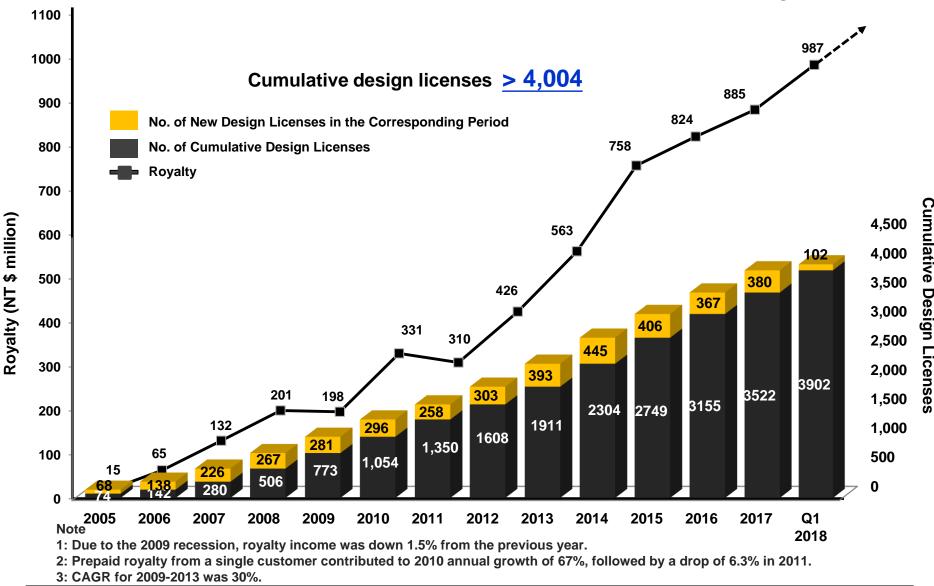
Note\*: As the applications of MCU at several foundries have gradually entered mass production, and the business model of the main foundry partner which provides green process has shifted to — eMemory licenses IP cell to the foundry for it to provide direct design service to customers as the result, the new tape out number of MCU has been affected, but the royalty coming from IP cell usage continues to roll in. In summary, even the new tape out number of MCU is lower than before; the corresponding wafer output and royalty continue to grow.

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### **Cumulative Licenses Drive Future Royalties**



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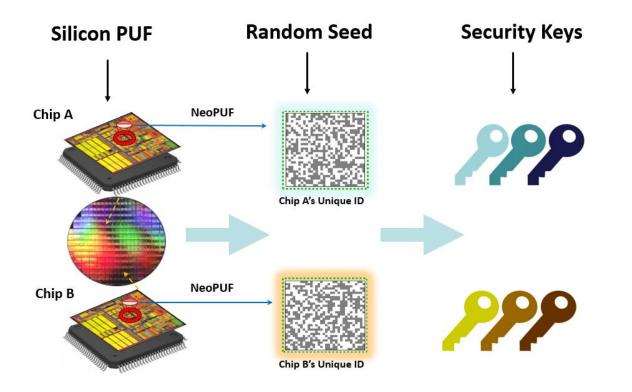
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## eMemory Technology – NeoPUF

 NeoPUF is inborn silicon PUF providing unique, truly random, multiple and configurable keys for authentication or anticounterfeits.

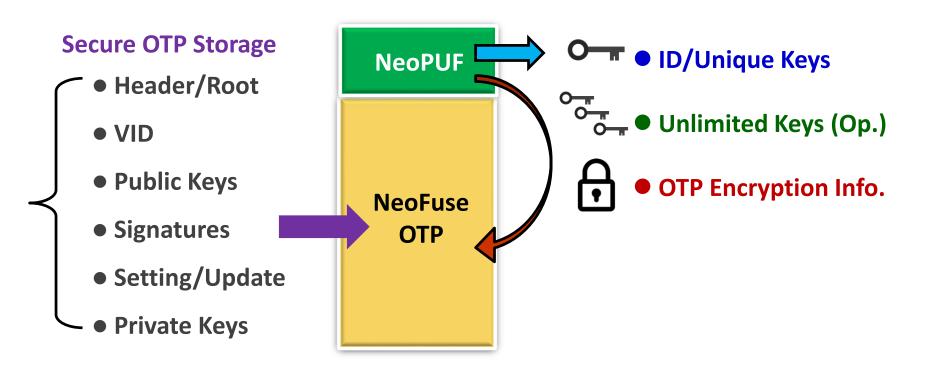


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## Integrated NeoFuse + NeoPUF

Solution for unique ID (secure memory) and supply chain management.





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### • Key drivers to licensing revenue:

- > Establishing partnerships with more foundries worldwide on various processes. This year, Korea's largest foundry is expected to be added on the list. Besides that, several new license contracts beyond 16nm platform are going to be signed in this year.
- > Our growing IP library will further contribute to growth of licensing revenue.
- > The increasing number of MTP license contracts will drive the growth of licensing revenue in the future.



### • Key drivers to royalty revenue :

### 8-inch processes

- > Royalty revenue which contribute from PMIC application will grow due to the change of business terms with US largest chipmaker from one-time fee to royalty-based, which is expected to mass production this year. And, the US second largest IC Design Company has taped out and embedded our IP into its wireless charger, will contribute royalty growth in the future.
- > MTP technology was adopted by a European IDM company, and is ready for mass production.
- > Continuing to expand our market share in Fingerprint application by new customers and new applications.
- > Increasing design activities of application in IOT, Automotive and healthcare related.

### 12-inch processes

- > The trend that DDI applications migrate to TDDI and OLED remains unchanged, will benefit to the revenue growth of 12inch processes.
- > More tape-outs at 28nm for Set-top box, multimedia, SSD controllers, and Network-related applications. Major Asia design houses have adopted our IP into their 28nm products and will contribute to our royalty in 2018 and beyond.

- Development of new applications
  - > NeoFuse solutions have successfully designed into DRAM IDM for memory repair function, starting from 25nm and beyond, will contribute to royalty in the future.
  - > NeoPUF is expected to work on RF, FPGA, portable POS machines, and cartridges related applications, will start contribute to royalty revenue in 2019.
- Development of new technologies
  - > We constantly cooperate with main foundries in development of IPs at 5/7/12/14nm and 22nm SOI platforms.
  - > We have started to co-develop new memory technology with a top IDM company in the US.



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### • Q & A



## **Q & A**



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